



## Materials Declaration Form


<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2020-11-05</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>MDG MD CHAMPION</b>	<b>Representative Title</b>	<b>MDG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement	
	<p>While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.</p>
Legal Statement	
<b>Supplier Acceptance *</b>	<b>true</b>
	<b>Legal Declaration *</b>
	<b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M93C66-RMC6TG	CGZW*0C661KA	A	P1C7	2020-11-05
	Amount	UoM	Unit type	ST ECOPACK Grade
	16.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2X3X0.6	8	No lead	
Comment	Package : ZW UFDFPN 2x3x0.6 8L 0.5MM PITCH 7558452			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product









Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CGZW*0C661KA				6000000.0	999989.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.371	mg	supplier	die	Silicon (Si)	7440-21-3		0.352	mg	948787	22000
				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	5391	125
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	2695	63
				supplier	Passivation	Silicon Oxide	7631-86-9		0.016	mg	43127	1000
Lead-frame	M-011 Other inorganic materials	3.007	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.918	mg	970270	182353
				supplier	alloy	Iron (Fe)	7439-89-6		0.070	mg	23358	4390
				supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	1195	225
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.003	mg	836	157
				supplier	coating	Nickel (Ni)	7440-02-0		0.012	mg	3980	748
				supplier	coating	Palladium (Pd)	7440-05-3		0.001	mg	255	48
				supplier	coating	Gold (Au)	7440-57-5		0.000	mg	106	20
Die Attach	M-011 Other inorganic materials	0.335	mg	supplier	glue or soft solder	Silver(Ag)	7440-22-4		0.268	mg	800000	16750
				supplier	glue or soft solder	Methylene diacrylate polymer	42594-17-2		0.055	mg	164000	3434
				supplier	glue or soft solder	Dicyclopentenylxyethyl methacrylate	68586-19-6		0.008	mg	25000	523
				supplier	glue or soft solder	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.002	mg	5000	105
				supplier	glue or soft solder	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.002	mg	5000	105
supplier	glue or soft solder	Palladium (Pd)	7440-05-3		0.000	mg	1000	21				
Wires	M-011 Other inorganic materials	0.011	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		0.011	mg	1000000	664
Encapsulation	M-011 Other inorganic materials	12.276	mg	supplier	Moulding Compound	Silica vitreous	60676-86-0		10.803	mg	880000	675180
				supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		0.614	mg	50000	38363
				supplier	Moulding Compound	Phenolic resin	205830-20-2		0.479	mg	39000	29923
				supplier	Moulding Compound	Epoxy type resin	Proprietary		0.246	mg	20000	15345
				supplier	Moulding Compound	Carbon black	1333-86-4		0.025	mg	2000	1535
supplier	Moulding Compound	other	Proprietary		0.110	mg	9000	6905				
Finishing	M-011 Other inorganic materials	0.000	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.000	mg	916800	7
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	0
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0







